

# DATA SHEET

## **TDA7073A; TDA7073AT** **Dual BTL power driver**

Product specification  
Supersedes data of 1994 July  
File under Integrated Circuits, IC01

1999 Aug 30

## Dual BTL power driver

## TDA7073A; TDA7073AT

## FEATURES

- No external components
- Very high slew rate
- Single power supply
- Short-circuit proof
- High output current (0.6 A)
- Wide supply voltage range
- Low output offset voltage
- Suited for handling PWM signals up to 176 kHz
- ESD protected on all pins.

## GENERAL DESCRIPTION

The TDA7073A/AT are dual power driver circuits in a BTL configuration, intended for use as a power driver for servo systems with a single supply. They are specially designed for compact disc players and are capable of driving focus, tracking, sled functions and spindle motors.

## Missing Current Limiter (MCL)

A MCL protection circuit is built-in. The MCL circuit is activated when the difference in current between the output terminal of each amplifier exceeds 100 mA (typical 300 mA). This level of 100 mA allows for headphone applications (single-ended).

## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_P$	positive supply voltage range		3.0	5.0	18	V
$G_V$	voltage gain		32.5	33.5	34.5	dB
$I_P$	total quiescent current	$V_P = 5\text{ V}; R_L = \infty$	–	8	16	mA
SR	slew rate		–	12	–	V/ $\mu$ s
$I_O$	output current		–	–	0.6	A
$I_{bias}$	input bias current		–	100	300	nA
$f_{co}$	cut-off frequency	–3 dB	–	1.5	–	MHz

## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA7073A	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SOT38-1
TDA7073AT	SO16	plastic small outline package; 16 leads; body width 7.5 mm	SOT162-1

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## BLOCK DIAGRAM

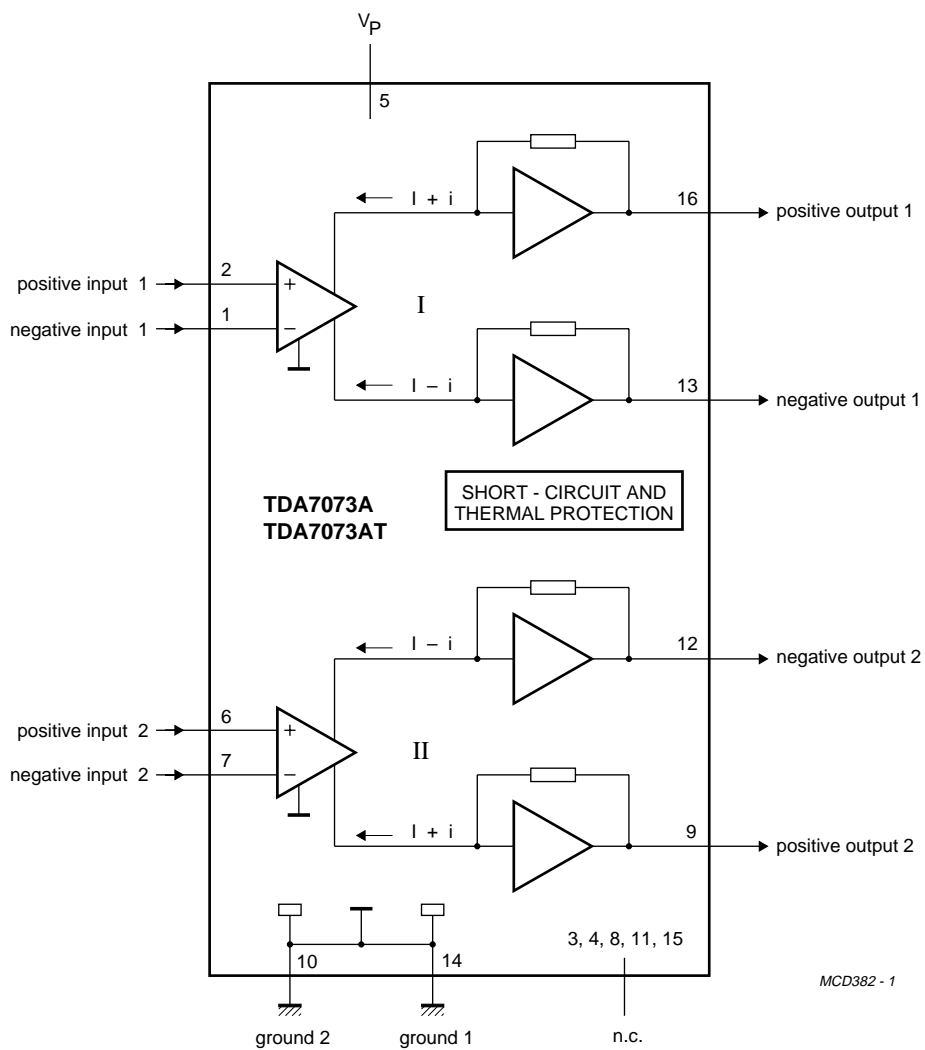


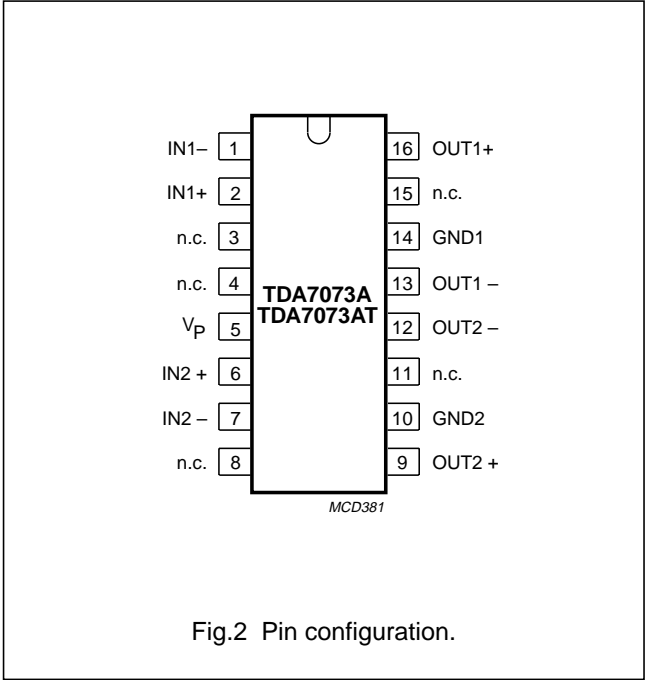
Fig.1 Block diagram.

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PINNING

SYMBOL	PIN	DESCRIPTION
IN1–	1	negative input 1
IN1+	2	positive input 1
n.c.	3	not connected
n.c.	4	not connected
V <sub>P</sub>	5	positive supply voltage
IN2+	6	positive input 2
IN2–	7	negative input 2
n.c.	8	not connected
OUT2+	9	positive output 2
GND2	10	ground 2
n.c.	11	not connected
OUT2–	12	negative output 2
OUT1–	13	negative output 1
GND1	14	ground 1
n.c.	15	not connected
OUT1+	16	positive output 1



FUNCTIONAL DESCRIPTION

The TDA7073A/AT are dual power driver circuits in a BTL configuration, intended for use as a power driver for servo systems with a single supply. They are particular designed for compact disc players and are capable of driving focus, tracking, sled functions and spindle motors.

Because of the BTL configuration, the devices can supply a bi-directional DC current in the load, with only a single supply voltage. The voltage gain is fixed by internal

feedback at 33.5 dB and the devices operate in a wide supply voltage range (3 to 18 V). The devices can supply a maximum output current of 0.6 A. The outputs can be short-circuited over the load, to the supply and to ground at all input conditions. The differential inputs can handle common mode input voltages from ground level up to ( $V_P - 2.2\text{ V}$  with a maximum of 10 V). The devices have a very high slew rate. Due to the large bandwidth, they can handle PWM signals up to 176 kHz.

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**LIMITING VALUES**

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_P$	positive supply voltage range		–	18	V
$I_{ORM}$	repetitive peak output current		–	1	A
$I_{OSM}$	non repetitive peak output current		–	1.5	A
$P_{tot}$	total power dissipation TDA7073A	$T_{amb} < 25\text{ °C}$	–	2.5	W
	TDA7073AT	$T_{amb} < 25\text{ °C}$	–	1.32	W
$T_{stg}$	storage temperature range		–55	+150	°C
$T_{vj}$	virtual junction temperature		–	150	°C
$T_{sc}$	short-circuit time	see note 1	–	1	hr

**Note**

1. The outputs can be short-circuited over the load, to the supply and to ground at all input conditions.

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	from junction to ambient			
	TDA7073A	in free air; note 1	50	K/W
	TDA7073AT	in free air; note 2	95	K/W

**Notes**

1. TDA7073A:  $V_P = 5\text{ V}$ ;  $R_L = 8\text{ }\Omega$ ; The typical voltage swing = 5.8 V and  $V_{loss}$  is 2.1 V therefore  $I_O = 0.36\text{ A}$  and  $P_{tot} = 2 \times 0.76\text{ W} = 1.52\text{ W}$ ;  $T_{amb(max)} = 150 - 1.52 \times 50 = 74\text{ °C}$ .
2. TDA7073AT:  $V_P = 5\text{ V}$ ;  $R_L = 16\text{ }\Omega$ ; typical voltage swing = 5.8 V and  $V_{loss}$  is 2.1 V therefore  $I_O = 0.18\text{ A}$  and  $P_{tot} = 2 \times 0.38\text{ W} = 0.76\text{ W}$ ;  $T_{amb(max)} = 150 - 0.76 \times 95 = 77\text{ °C}$ .

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## CHARACTERISTICS

$V_P = 5\text{ V}$ ;  $f = 1\text{ kHz}$ ;  $T_{\text{amb}} = 25\text{ °C}$ ; unless otherwise specified (see Fig.3). TDA7073A:  $R_L = 8\text{ }\Omega$ ; TDA7073AT:  $R_L = 16\text{ }\Omega$ .

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_P$	positive supply voltage range		3.0	5.0	18	V
$I_{\text{ORM}}$	repetitive peak output current		—	—	0.6	A
$I_P$	total quiescent current	$V_P = 5\text{ V}$ ; $R_L = \infty$ ; note 1	—	8	16	mA
$\Delta V_{\text{OUT}}$	output voltage swing	note 2	5.2	5.8	—	V
THD	total harmonic distortion					
	TDA7073A TDA7073AT	$V_{\text{OUT}} = 1\text{ V (RMS)}$ $V_{\text{OUT}} = 1\text{ V (RMS)}$	— —	0.3 0.1	— —	% %
$G_V$	voltage gain		32.5	33.5	34.5	dB
$V_{\text{no(rms)}}$	noise output voltage (RMS value)	note 3	—	75	150	$\mu\text{V}$
B	bandwidth		—	—	1.5	MHz
SVRR	supply voltage ripple rejection	note 4	38	55	—	dB
$ \Delta V_{16-13,12-9} $	DC output offset voltage	$R_S = 500\text{ }\Omega$	—	—	100	mV
$V_{\text{I(CM)}}$	DC common mode voltage range	note 5	0	—	2.8	V
CMRR	DC common mode rejection ratio	note 6	—	100	—	dB
$Z_i$	input impedance		—	100	—	k $\Omega$
$I_{\text{bias}}$	input bias current		—	100	300	nA
$\alpha$	channel separation		40	50	—	dB
$ \Delta\text{GV} $	channel unbalance		—	—	1	dB
SR	slew rate		—	12	—	V/ $\mu\text{s}$

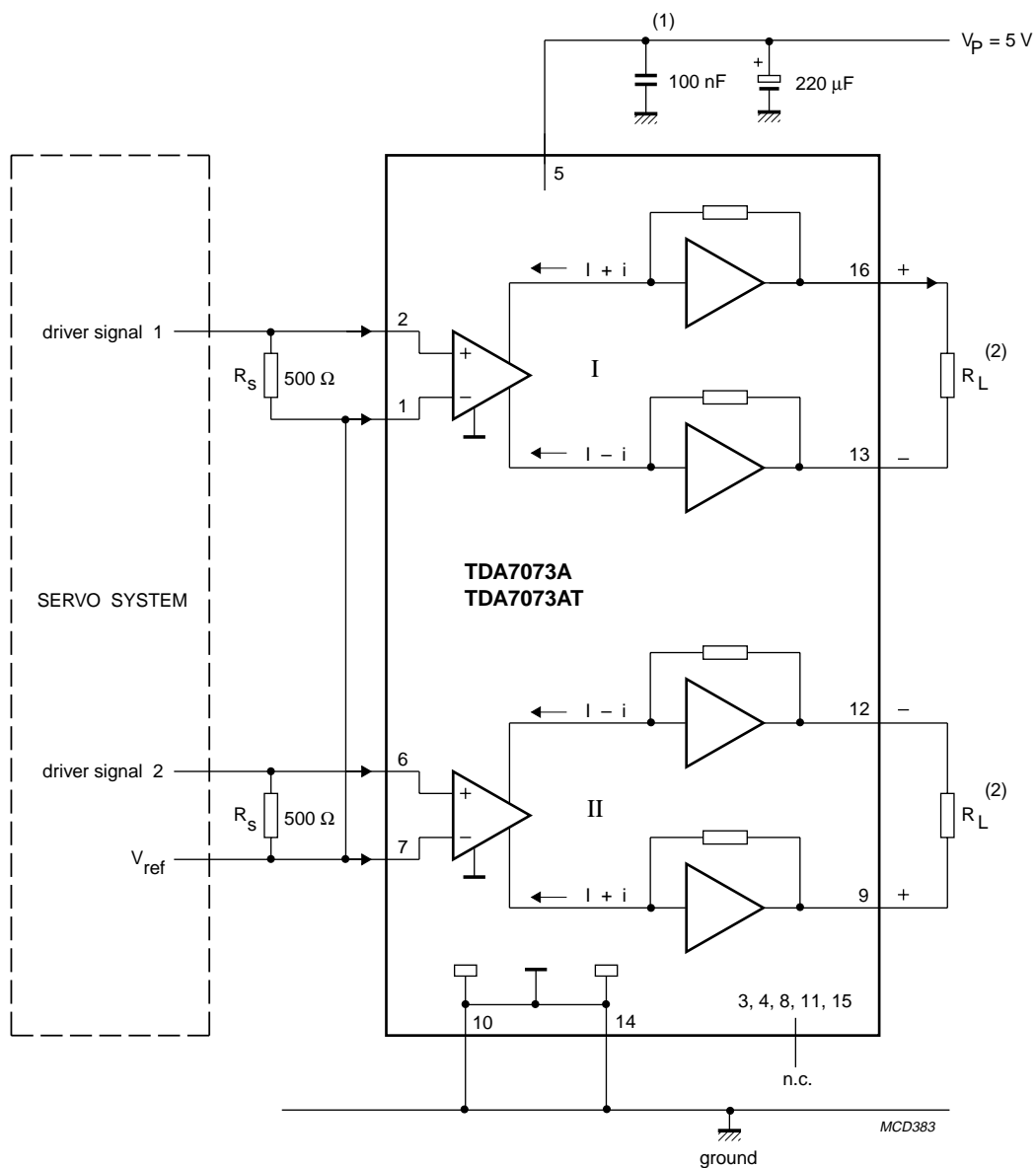
## Notes

1. With a load connected to the outputs the quiescent current will increase, the maximum value of this increase being equal to the DC output offset voltage divided by  $R_L$ .
2. The output voltage swing is typically limited to  $2 \times (V_P - 2.1\text{ V})$  (see Fig.4).
3. The noise output voltage (RMS value), unweighted (20 Hz to 20 kHz) is measured with  $R_S = 500\text{ }\Omega$ .
4. The ripple rejection is measured with  $R_S = 0\text{ }\Omega$  and  $f = 100\text{ Hz}$  to  $10\text{ kHz}$ . The ripple voltage of  $200\text{ mV}$  (RMS value) is applied to the positive supply rail.
5. The DC common mode voltage range is limited to  $(V_P - 2.2\text{ V})$  with a maximum of  $10\text{ V}$ .
6. The common mode rejection ratio is measured at  $V_{\text{ref}} = 1.4\text{ V}$ ,  $V_{\text{I(CM)}} = 200\text{ mV}$  and  $f = 1\text{ kHz}$ .

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## APPLICATION INFORMATION

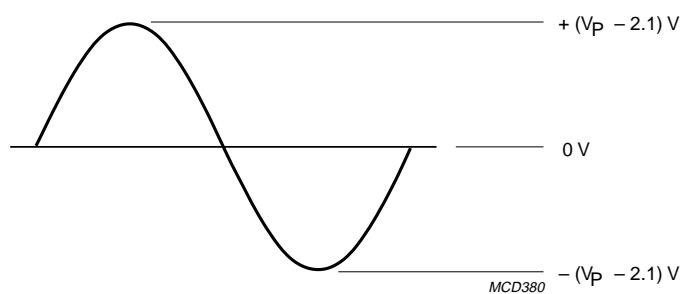


- (1) This capacitor can be omitted if the 220 μF electrolytic capacitor is connected close to pin 5.  
 (2)  $R_L$  can be: focus, tracking, sled function or spindle motor.

Fig.3 Test and application diagram.

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Fig.4 Typical output voltage swing over  $R_L$ .

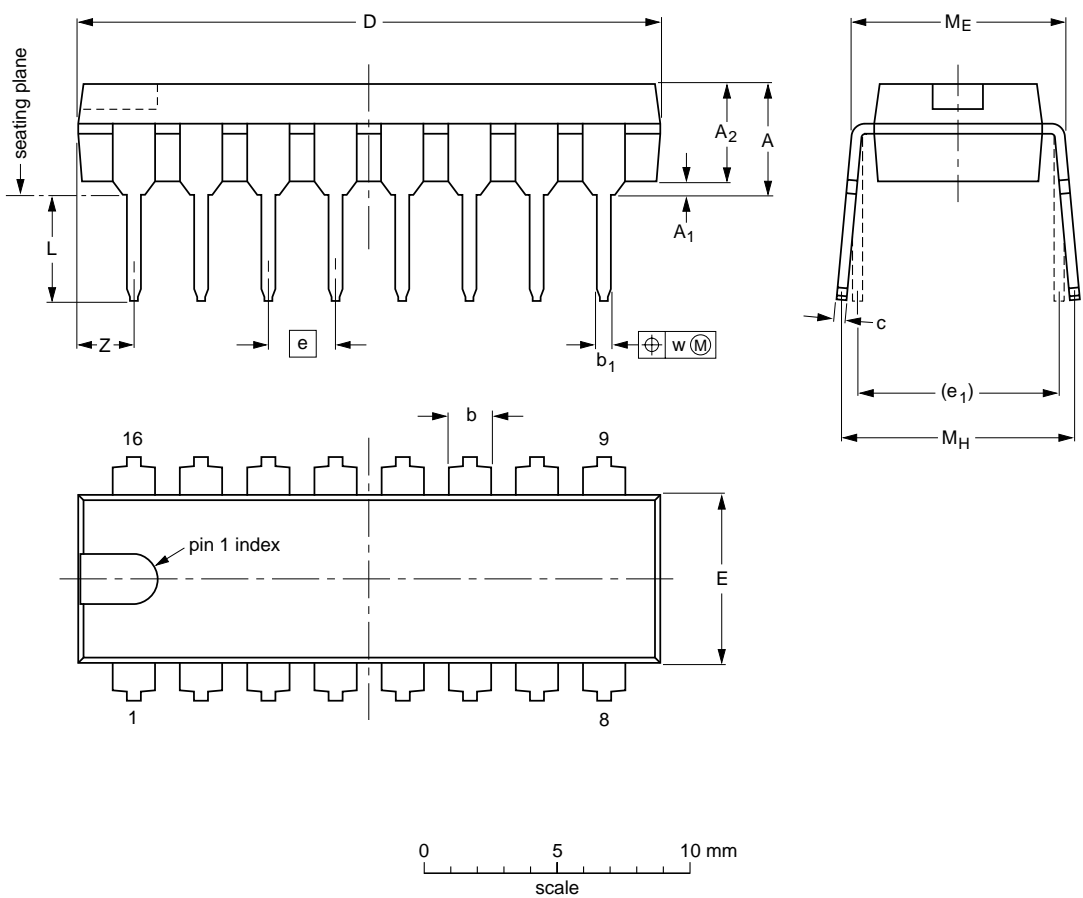
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PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1




DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.020	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.10	0.30	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

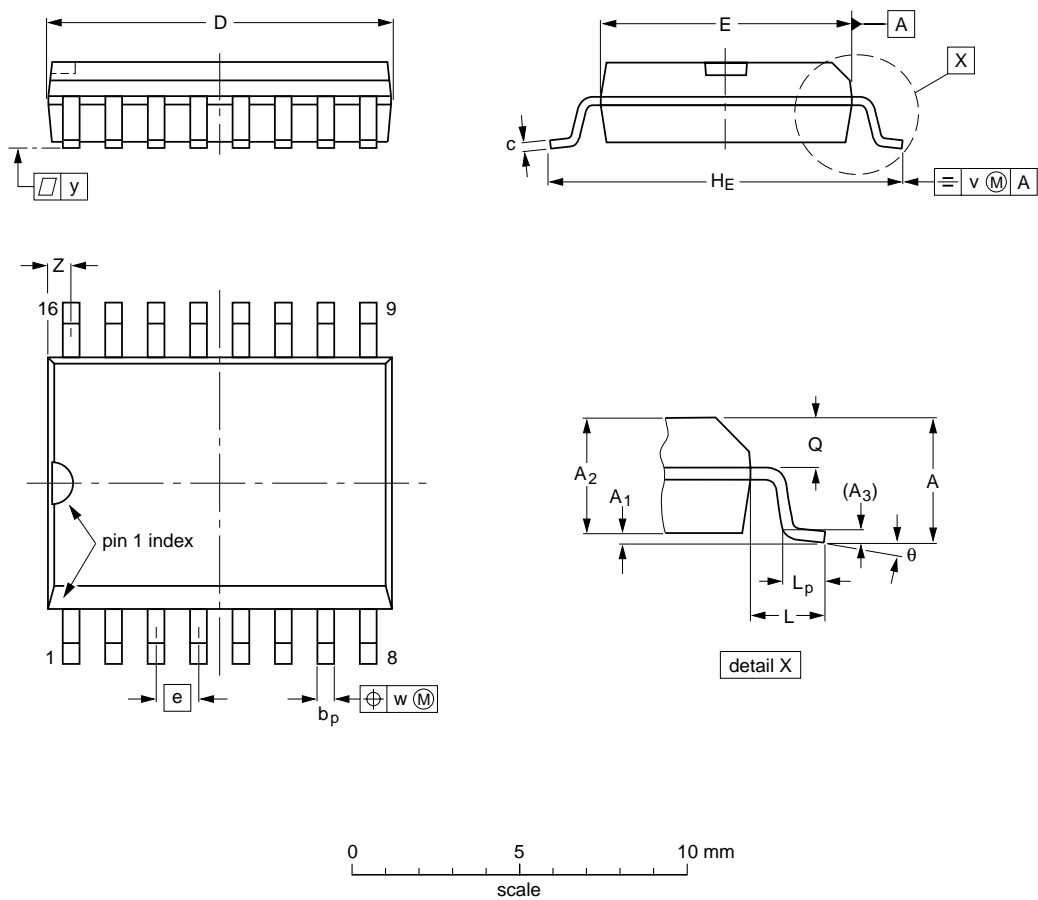
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-1	050G09	MO-001AE				92-10-02- 95-01-19

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SO16: plastic small outline package; 16 leads; body width 7.5 mm

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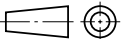


DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT162-1	075E03	MS-013AA				95-01-24 97-05-22

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**SOLDERING****Introduction**

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mount components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

**Through-hole mount packages****SOLDERING BY DIPPING OR BY SOLDER WAVE**

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joints for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg(max)}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

**MANUAL SOLDERING**

Apply the soldering iron (24 V or less) to the lead(s) of the package, either below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

**Surface mount packages****REFLOW SOLDERING**

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

**WAVE SOLDERING**

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

**MANUAL SOLDERING**

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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## Suitability of IC packages for wave, reflow and dipping soldering methods

MOUNTING	PACKAGE	SOLDERING METHOD		
		WAVE	REFLOW <sup>(1)</sup>	DIPPING
Through-hole mount	DBS, DIP, HDIP, SDIP, SIL	suitable <sup>(2)</sup>	–	suitable
Surface mount	BGA, LFBGA, SQFP, TFBGA	not suitable	suitable	–
	HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, SMS	not suitable <sup>(3)</sup>	suitable	–
	PLCC <sup>(4)</sup> , SO, SOJ	suitable	suitable	–
	LQFP, QFP, TQFP	not recommended <sup>(4)(5)</sup>	suitable	–
	SSOP, TSSOP, VSO	not recommended <sup>(6)</sup>	suitable	–

## Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the “*Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods*”.
2. For SDIP packages, the longitudinal axis must be parallel to the transport direction of the printed-circuit board.
3. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
5. Wave soldering is only suitable for LQFP, QFP and TQFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
6. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

## DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

## LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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**NOTES**

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